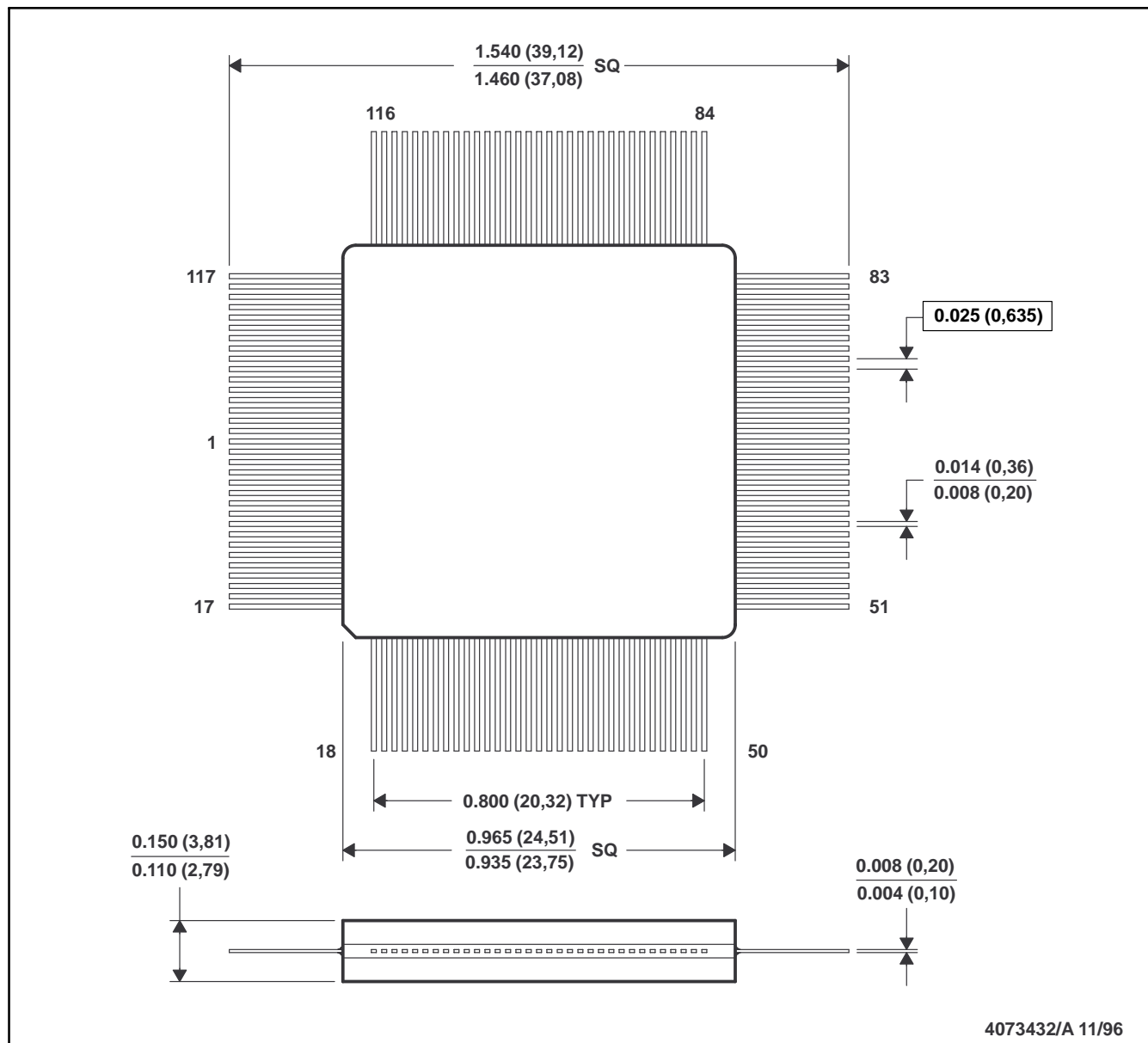


HFP (S-GQFP-F132)

CERAMIC QUAD FLATPACK



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.

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